I below certify that this correspondence is being deposited with the U.S. Postal dervice with sufficient postage as First Class Mail, in an envelope addressed to:

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Tow

Docket No.: TESSERA 3.0-272

(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

(Arnold H. Krumholz)

In re Patent Application of:

22313-1450, on the date shown below.

Delin Li

Group Art Unit: 2818

Serial No.: 10/611,390

Dated: May 24, 2005

Confirmation No.: 1533

Filed: July 1, 2003

Examiner: M. H. C. Tran

For: ASSEMBLIES HAVING STACKED

SEMICONDUCTOR CHIPS AND METHODS

OF MAKING SAME

SUBMISSION OF FORMAL DRAWINGS

MS ISSUE FEE Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Enclosed herewith are four (4) replacement sheets of formal drawings for filing in connection with the above-identified patent application. The formal drawings are submitted in order to correct the informalities listed in form PTO-948.

In the event there are any fees due or owing in connection with this matter, please charge same to our Deposit Account No. 12-1095.

Dated: May 24, 2005

Respectfully submitted,

Arnold H. Krumholz

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